ADLINK
LEADING EDGE AI COMPUTING

I-Pi OSM iMX95

I-Pi OSM Development Kit Based on NXP® i.MX95 Hexa-Core Arm® Cortex-A55, Arm® Cortex-M7 & Cortex-M33



Features

- OSM-EB4 carrier
- OSM-iMX95 module powered by NXP® i.MX95 with hexa-core Arm® Cortex-A55, Arm® Cortex-M7 & Cortex-M33
- In-SoC NXP eIQ Neutron N3 NPU, up to 2.0 TOPS
- 4GB LPDDR4 soldered, 32GB eMMC
- HDMI, DSI, dual LVDS graphic outputs
- Dual GbE (TSN capable), dual CAN bus FD, USB3.0, USB 2.0, USB 2.0 OTG
- Rugged operating temperature (optional): -40°C to +85°C

Specifications

Core System	SoC	NXP i.MX95 hexa-core Arm Cortex-A55, Cortex-M7 & Cortex-M33
	NPU	eIQ Neutron N3 NPU, up to 2.0 TOPS
	Architecture	6x Arm® Cortex-A55 + 1x Arm® Cortex-M7 + 1x Arm® Cortex-M33
	Memory	4GB LPDDR4
	Storage	32GB eMMC
	Security	Arm® TrustZone®
Video	GPU Core	Arm Mali-G310
	HDMI	1x HDMI interface
	MIPI DSI	1x MIPI DSI via LVDS connector, 4 lanes
	LVDS	2x LVDS interface, 8 lanes
	Camera	1x 22-pin CSI connector, 4 lanes
Audio	Codec	TI TLV320
Ethernet	LAN	2x GbE (TSN capable)

Note: "Build option" indicates an alternative BOM configuration to support additional or alternative functions that are not available on the standard product. Be aware that these "build option" part numbers will need to be newly created and this will result in production lead times.

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Specifications

Connectors/Headers	Display	1x HDMI
		2x LVDS
	Audio	1x 3.5mm Audio jack
	Network	2x RJ45
	USB	2x USB 2.0 Host,2x USB 3.0 Host, 1x USB 2.0 OTG
	SD Card Slot	1x microSD
	M.2 Card Slots	1x M.2 M-key PCIe
	UART	5x UART on header
	SPI	3x SPI on header
	I^2C	2x I2C on header
	GPIO	14x GPIO on header
	PWM	4x PWM on header
	ADC	2x ADC on header
Power	Input	19V+/-5% DC (Adapter: 19VDC)
	Connector	DC jack
Operating Systems	Standard Support	Yocto Linux BSP
Mechanical and Environmental	Form Factor	4" EPIC
	Dimensions	165 mm x 115 mm
	Operating Temperature	Standard: 0°C to +60°C Rugged: -40°C to +85°C (optional)
	Humidity	5-90% RH operating, non-condensing 5-95% RH storage (and operating with conformal coating)
	Shock and Vibration	IEC 60068-2-64 and IEC-60068-2-27, MIL-STD-202 F, Method 213B, Table 213-I, Condition A and Method 214A, Table 214-I, Condition D

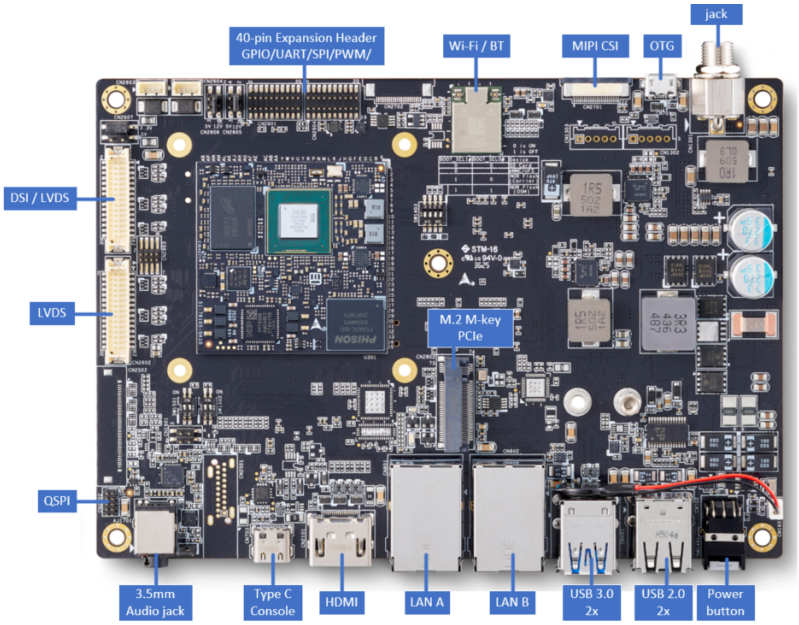
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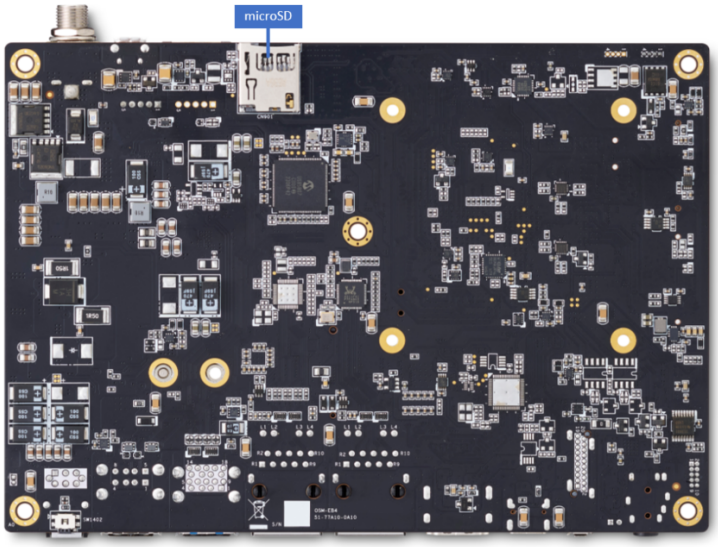
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Ordering Information

Part Name	Description/Configuration
OSM-IMX95-H-4G-32G-CT	OSM module L size with six core NXP i.mx95, NPU, 4 GB LPDDR4, 32 GB eMMC, 0°C to 60°C
OSM-iMX95-H-4G-32G-ER	OSM module L size with six core NXP i.mx95, NPU, 4 GB LPDDR4, 32 GB eMMC, -40°C to 85°C
I-Pi OSM-iMX95-4G-32G	I-Pi OSM prototype kit with OSM-iMX95-H-4G-32G-CT (US & EU power cable, 110/220V to 19V adapter, USB debug cable)

Note: Non-listed configurations are available upon request.





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